INTEGRATED CIRCUITS



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1 FEATURES

1.1 Hardware

- 5-bitstream 3rd-order sigma-delta Analog-to-Digital Converters (ADCs) with anti-aliasing broadband input filter
- 1-bitstream 1st-order sigma-delta ADC with anti-aliasing broadband input filter
- 4-bitstream Digital-to-Analog Converters (DACs) with 128-fold oversampling and noise shaping
- Integrated semi-digital filter; no external post filter required for DAC
- Dual media support: allowing separate front-seat and rear-seat signal sources and separate control
- Simultaneous radio and audio processing
- Digital FM stereo decoder
- Digital FM interference suppression
- RDS demodulation via separate ADC; with buffered output option
- Two mono Common-Mode Rejection Ratio (CMRR) input stages for voice signals from phone and navigation inputs
- Phone and navigation mixing at DAC front outputs
- Two stereo CMRR input stages (CD-walkman and CD-changer etc.)
- Analog single-ended TAPE and AUX input
- Separate AM-left and AM-right inputs in the event of use of external AM stereo decoder
- One digital input: I²S-bus or LSB-justified format
- Two digital inputs: SPDIF format
- Co-DSP support via I²S-bus or LSB-justified format
- Audio output short-circuit protected
- I²C-bus controlled (including fast mode)
- · MOST bus interfacing (details in separate manual)
- Phase-locked loop derives the internal clocks from one common fundamental crystal oscillator
- Combined AM/FM level input
- Pin compatible with SAA7705 and SAA7708
- · All digital inputs are tolerant of 5 V input levels
- All analog inputs have high GSM immunity
- Low number of external components required
- -40 to +85 °C operating temperature range



1.2 Software

- Improved FM weak signal processing
- Integrated 19 kHz MPX filter; de-emphasis and stereo detection
- Electronic adjustments: FM or AM level, FM channel separation, Dolby®⁽¹⁾ level
- Baseband audio processing (treble, bass, balance, fader and volume)
- · Four channel 5-band parametric equalizer
- · 9-bands mono audio spectrum analyzer
- Extended beep functions with tone sequencer for phone rings
- Large volume jumps e-power interpolated to prevent zipper noise
- Dual media support; allowing separate front-seat and rear-seat signal sources and separate control
- Dynamic loudness or bass boost
- Audio level monitor
- Tape equalization and Music Search System (MSS) detection for tape
- Dolby-B tape noise reduction (at 44.1 kHz only)
- Dynamics compression available in all modes
- CD de-emphasis processing
- Voice-over possibility for phone and navigation signals
- Improved AM signal processing
- Digital AM CQUAM stereo decoder (not in all rom_codes available)
- Digital AM interference suppression
- Soft audio mute
- RDS update processing: pause detection, mute and signal-quality sensor-freeze
- · General purpose tone generator
- (1) Dolby Available only to licensees of Dolby Laboratories Licensing Corporation, San Francisco, CA94111, USA, from whom licensing and application information must be obtained. Dolby is a registered trade-mark of Dolby Laboratories Licensing Corporation.



SAA7706H

- Noise generator allows for frequency response measurements
- Boot-up ROM for fast start-up
- Signal level, noise and multipath detection for AM or FM signal quality information
- AM co-channel and adjacent channel detection (not in all rom_codes available).

2 APPLICATIONS

• High-end car radio systems.

3 GENERAL DESCRIPTION

The SAA7706H performs all the signal functions in front of the power amplifiers and behind the car radio tuner AM and FM outputs and the CD, tape and phone inputs. These functions are:

- Interference absorption
- Stereo decoding for FM and AM (stereo)

4 QUICK REFERENCE DATA

- RDS-demodulation
- FM and AM weak signal processing (soft mute, sliding stereo and high cut)
- Dolby-B tape noise reduction
- CD de-emphasis function
- Audio controls for volume, balance, fader, tone and dynamics compression.

Some functions have been implemented in hardware (FM stereo decoder, RDS-demodulator and FM Interference Absorption Circuit (IAC) and are not freely programmable.

Digital audio signals from external sources with the Philips I²S-bus and the LSB-justified 16, 18, 20 and 24 bits format or SPDIF format are accepted.

The big advantage of this SAA7706H device is the 'dual media support'; this enables independent front seat and rear seat audio sources and control.

PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
				•	
operating supply voltage	all V_{DD} pins with respect to V_{SS}	3	3.3	3.6	V
supply current of the digital part	DSP1 at 50 MHz; DSP2 at 62.9 MHz	-	110	150	mA
supply current of the analog part	zero input and output signal	-	40	60	mA
total power dissipation	DSP1 at 50 MHz; DSP2 at 62.9 MHz	-	540	750	mW
		•	•	•	•
maximum conversion input level (RMS value)	THD < 1%; VOLFM = 00H	0.33	0.368	-	V
total harmonic distortion	input signal 0.368 V	-	-70	-65	dB
	(RMS) at 1 kHz; bandwidth = 19 kHz; VOLFM = 00H	-	0.03	0.056	%
signal-to-noise ratio input stereo	input signal at 1 kHz; bandwidth = 40 kHz; 0 dB reference = 0.368 V (RMS); VOLFM = 00H	75	81	_	dB
(and AM inputs					
maximum conversion input level (RMS value)	THD < 1%	0.6	0.66	-	V
	operating supply voltage supply current of the digital part supply current of the analog part total power dissipation maximum conversion input level (RMS value) total harmonic distortion signal-to-noise ratio input stereo C and AM inputs maximum conversion input level	operating supply voltage all V _{DD} pins with respect to V _{SS} supply current of the digital part DSP1 at 50 MHz; DSP2 at 62.9 MHz supply current of the analog part zero input and output signal total power dissipation DSP1 at 50 MHz; DSP2 at 62.9 MHz maximum conversion input level THD < 1%; VOLFM = 00H	operating supply voltageall VDD pins with respect to VSS3supply current of the digital partDSP1 at 50 MHz; DSP2 at 62.9 MHz-supply current of the analog partzero input and output signal-total power dissipationDSP1 at 50 MHz; DSP2 at 62.9 MHz-maximum conversion input levelTHD < 1%; VOLFM = 00H	operating supply voltageall VDD pins with respect to VSS33.3supply current of the digital partDSP1 at 50 MHz; DSP2 at 62.9 MHz-110supply current of the analog partzero input and output signal-40total power dissipationDSP1 at 50 MHz; DSP2 at 62.9 MHz-540maximum conversion input level (RMS value)THD < 1%; VOLFM = 00H	operating supply voltageall V_{DD} pins with respect to V_{SS} 33.33.6supply current of the digital partDSP1 at 50 MHz; DSP2 at 62.9 MHz-110150supply current of the analog partzero input and output signal-4060total power dissipationDSP1 at 50 MHz; DSP2 at 62.9 MHz-540750maximum conversion input level (RMS value)THD < 1%; VOLFM = 00H0.330.368-total harmonic distortioninput signal 0.368 V (RMS) at 1 kHz; bandwidth = 19 kHz; VOLFM = 00H70-65signal-to-noise ratio input stereoinput signal at 1 kHz; bandwidth = 40 kHz; 0 dB reference = 0.368 V (RMS); VOLFM = 00H7581-Cand AM inputsmaximum conversion input levelTHD < 1%

SAA7706H

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
THD	total harmonic distortion	input signal 0.55 V (RMS) at 1 kHz; bandwidth = 20 kHz	-	-85	-75	dB
S/N	signal-to-noise ratio	input signal at 1 kHz; bandwidth = 20 kHz; 0 dB reference = 0.55 V (RMS)	85	90	-	dB
FSDAC		•	•			
(THD + N)/S	total harmonic distortion-plus-noise to	at 0 dB	-	-90	-85	dB
	signal ratio (measured with system one)	at –60 dB; A-weighted	-	-37	-	dB
S/N	signal-to-noise ratio (measured with system one)	code = 0; A-weighted	-	105	-	dB
Crystal oscilla	ator	•				
f _{xtal}	crystal frequency		_	11.2896	_	MHz

5 ORDERING INFORMATION

TYPE	PACKAGE					
NUMBER	NAME	DESCRIPTION	VERSION			
SAA7706H	QFP80	plastic quad flat package; 80 leads (lead length 1.95 mm); body $14 \times 20 \times 2.8$ mm	SOT318-2			



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Philips Semiconductors

SAA7706H

Car radio Digital Signal Processor (DSP)

Product specification

o

SAA7706H

7 PINNING

SYMBOL	PIN	PIN TYPE	DESCRIPTION
VDACP	1	apio	positive reference voltage ADC1, ADC2, ADC3 and level-ADC
VDACN1	2	apio	ground reference voltage ADC1
LEVEL	3	apio gsmcap	LEVEL input pin; via this pin the level of the FM signal or level of the AM signal is fed to the DSP1; the level information is used in the DSP1 for dynamic signal processing
NAV_GND	4	apio gsmcap	common mode reference input pin of the navigation signal (pin AM_L/NAV)
POM	5	apio	power-on mute of the QFSDAC; timing is determined by an external capacitor
RRV	6	apio	rear; right audio output of the QFSDAC
AUX_L	7	apio	left channel of analog AUX input
AUX_R	8	apio	right channel of analog AUX input
RLV	9	apio	rear; left audio output of the QFSDAC
V _{SSA2}	10	VSSCO	ground supply analog part of the QFSDAC and SPDIF bitslicer
V _{DDA2}	11	vddco	positive supply analog part of the QFSDAC and SPDIF bitslicer
VREFDA	12	apio	voltage reference of the analog part of QFSDAC
FRV	13	apio	front; right audio output of the QFSDAC
CD_R_GND	14	apio	common-mode reference input pin for analog CD_R or TAPE_R in the event of separated ground reference pins for left and right are used
DSP2_INOUT2	15	bpts5thdt5v	flag input/output 2 of the DSP2-core (DSP2-flag) I ² C-bus configurable
FLV	16	apio	front; left audio voltage output of the QFSDAC
DSP2_INOUT1	17	bpts5thdt5v	flag input/output 1 of the DSP2-core (DSP2-flag) I ² C-bus configurable
DSP2_INOUT3	18	bpts5thdt5v	flag input/output 3 of the DSP2-core (DSP2-flag) I ² C-bus configurable
DSP2_INOUT4	19	bpts5thdt5v	flag input/output 4 of the DSP2-core (DSP2-flag) I ² C-bus configurable
LOOPO	20	bpts5tht5v	SYSCLK output (256fs)
TP1	21	ipthdt5v	for test purpose only; this pin may be left open or connected to ground
V _{DDD3V7}	22	vdde	positive supply (peripheral cells only)
V _{SSD3V7}	23	vsse	ground supply (peripheral cells only)
SPDIF2	24	apio	SPDIF input 2; can be selected instead of SPDIF1 via I ² C-bus bit
SPDIF1	25	apio	SPDIF input 1; can be selected instead of SPDIF2 via I ² C-bus bit
SYSFS	26	ipthdt5v	system fs clock input
CD_WS	27	ipthdt5v	digital CD-source word select input; I ² S-bus or LSB-justified format
CD_DATA	28	bpts10thdt5v	digital CD-source left-right data input; I ² S-bus or LSB-justified format
CD_CLK	29	ipthdt5v	digital CD-source clock input I ² S-bus or LSB-justified format
IIS_CLK	30	ots10ct5v	clock output for external I ² S-bus receiver; for example headphone or subwoofer
IIS_IN1	31	ipthdt5v	data 1 input for external I ² S-bus transmitter; e.g. audio co-processor
IIS_IN2	32	ipthdt5v	data 2 input for external I ² S-bus transmitter; e.g. audio co-processor
IIS_WS	33	ots10ct5v	word select output for external I ² S-bus receiver; for example headphone or subwoofer
IIS_OUT1	34	ots10ct5v	data 1 output for external I ² S-bus receiver or co-processor
IIS_OUT2	35	ots10ct5v	data 2 output for external I ² S-bus receiver or co-processor

VssDave 37 vsse ground supply (peripheral cells only) DSP1_IN1 38 bpts10tht5v flag input 2 of the DSP1-core DSP1_UT1 40 op4mc flag output 1 of the DSP1-core DSP1_OUT2 41 op4mc flag output 1 of the DSP1-core DSP_RESET 42 ipth45v general reset of chip (active LOW) RTCB 43 ipth45v synchronous reset test control block; connect to ground (internal pull-down) SHTCB 44 ipth45v ssinchronous reset test control block (internal pull-down) Vpccovs 46 vsse ground supply (peripheral cells only) Vssbavs 47 vsse ground supply (core only) Vssbavs 47 vsse ground supply (core only) Vssbavs 49 vssis ground supply (core only) Vssbavs 51 vddo positive supply (core only) Vssbavs 53 vssco ground supply (core only) Vssbavs 53 vssco ground supply (core only) Vssbavs 54 vssis	SYMBOL	PIN	PIN TYPE	DESCRIPTION	
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DSP1_IN2 39 bpts10thdt5v flag input 2 of the DSP1-core DSP1_OUT1 40 op4mc flag output 1 of the DSP1-core DSP1_OUT2 41 op4mc flag output 2 of the DSP1-core DSP_RESET 42 ipthdfsv general reset of chip (active LOW) RTCB 43 ipthdfsv saynchronous reset test control block; connect to ground (internal pull-down) STCAN 45 ipthdfsv scan control active high (internal pull-down) VDD3V5 46 vdde positive supply (peripheral cells only) Vsstavs 47 vsse ground supply (core only) Vsstavs 47 vsse ground supply (core only) Vsstavz 50 vssco ground supply (core only) Vsstavz 50 vssco ground supply (core only) Vsstavz 51 vddco positive supply (core only) Vsstavz 52 vddco positive supply (core only) Vsstavz 53 vssco ground supply (core only) Vsstavz 54 vssis ground s	V _{SSD3V6}	37	vsse	ground supply (peripheral cells only)	
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VDDD3V5 46 Vdde positive supply (peripheral cells only) VSD3V5 47 vsse ground supply (peripheral cells only) VDD3V1 48 vddi positive supply (core only) VSD3V1 49 vssis ground supply (core only) VSD3V1 49 vssco ground supply (core only) VSD3V2 50 vssco ground supply (core only) VDD3V3 51 vddco positive supply (core only) VDD3V3 52 vddco positive supply (core only) VSD3V4 54 vssis ground supply (core only) VDD3V4 55 vddi positive supply (core only) VDD3V4 56 ipthd5v slave sub-address I2C-bus selection or serial data input test control block SCL 57 iptht5v serial data input/output I2C-bus RDS_CLOCK 59 bpts10th5v radio data system data output RDS_DATA 60 ops10c radio data system data output VScosc) 62 vssco ground supply (crystal oscillator only) </td <td>SHTCB</td> <td>44</td> <td>ipthdt5v</td> <td>shift clock test control block (internal pull-down)</td>	SHTCB	44	ipthdt5v	shift clock test control block (internal pull-down)	
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CD_R 70 apio gsmcap right channel of analog CD input PHONE 71 apio gsmcap common mode PHONE signal, analog input pin	TAPE_R	68	apio gsmcap	right channel of analog TAPE input	
PHONE 71 apio gsmcap common mode PHONE signal, analog input pin	TAPE_L	69	apio gsmcap	left channel of analog TAPE input	
	CD_R	70	apio gsmcap		
CD_L 72 apio gsmcap left channel of analog CD input	PHONE	71	apio gsmcap		
	CD_L	72	apio gsmcap	left channel of analog CD input	

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SYMBOL	PIN	PIN TYPE	DESCRIPTION
PHONE_GND	73	apio gsmcap	common mode reference input pin of the PHONE signal
V _{DDA1}	74	vddco	positive supply analog (ADC1, ADC2, ADC3 and level-ADC only)
V _{SSA1}	75	VSSCO	ground supply analog (ADC3 and level-ADC only)
VDACN2	76	apio	ground reference voltage (ADC2)
CD_(L)_GND	77	apio gsmcap	common mode reference input pin for analog CD or TAPE or in the event of separated ground reference pins used for CD_L or TAPE_L
VREFAD	78	apio	common mode reference voltage ADC1, ADC2, ADC3 and level-ADC
FM_RDS	79	apio gsmcap	FM RDS signal; analog input pin
FM_MPX	80	apio gsmcap	FM multiplex signal; analog input pin

Table 1 Brief explanation of used pin types

PIN TYPE	EXPLANATION
apio	3-state I/O analog; I/O pad cell; actually pin type vddco
apio gsmcap	3-state I/O analog; I/O pad cell; actually pin type vddco with high GSM immunity
bpts5thdt5v	43 MHz bidirectional pad; push-pull input; 3-state output; 5 ns slew rate control; TTL; hysteresis; pull-down; 5 V tolerant
bpts10tht5v	21 MHz bidirectional pad; push-pull input; 3-state output; 10 ns slew rate control; TTL; hysteresis; 5 V tolerant
bpts10thdt5v	21 MHz bidirectional pad; push-pull input; 3-state output; 10 ns slew rate control; TTL; hysteresis; pull-down; 5 V tolerant
iic400kt5∨	I ² C-bus pad; 400 kHz I ² C-bus specification; TTL; 5 V tolerant
iptht5v	input pad buffer; TTL; hysteresis; 5 V tolerant
ipthdt5v	input pad buffer; TTL; hysteresis; pull-down; 5 V tolerant
iptut5∨	input pad buffer; TTL; pull-up; 5 V tolerant
op4mc	output pad buffer; 4 mA output drive; CMOS; slew rate control; 50 MHz
ots10ct5v	output pad buffer; 3-state, 10 ns slew rate control; CMOS; 5 V tolerant
ops10c	output pad buffer; 4 mA output drive; CMOS; slew rate control; 21 MHz
vdde	V _{DD} supply peripheral only
vsse	V _{SS} supply peripheral only
vddco	V _{DD} supply to core only
VSSCO	V _{SS} supply to core only (vssco does not connect the substrate)
vddi	V _{DD} supply to core and peripheral
vssis	V _{SS} supply to core and peripheral; with substrate connection





8 FUNCTIONAL DESCRIPTION

8.1 Analog front-end

The analog front-end consists of two identical sigma-delta stereo ADCs (ADC1 and ADC2) with several input control blocks for handling common mode signals and acting as input selector. A mono version (ADC3) is added for handling RDS signals. Also a first-order sigma-delta ADC for tuner level information is incorporated.

The switches S1 and S2 select (see Fig.3) between the FM_MPX/FM_RDS and the CD, TAPE, AUX, AM, PHONE and NAV connection to ADC1 and ADC2. The inputs CD, TAPE, AUX, AM, PHONE and NAV can be selected with the audio input controls (AIC1/2). The ground reference (G0 and G1) can be selected to be able to handle common mode signals for CD or TAPE. The ground reference G0 is connected to an external pin and G1 is internally referenced (see Fig.4).

The PHONE and NAV inputs have their own CMRR input stage and can be redirected to ADC1/2 via the Audio Input Control (AIC). For pin compatibility with SAA7704, SAA7705 and SAA7708 the AM is combined with the NAV input. It is also possible to directly mix PHONE or NAV (controlled with MIXC) with the front FSDAC channels after volume control. The FM inputs (FM_MPX/FM_RDS) can be selected with external pin SEL_FR. The FM and RDS input sensitivity can be adjusted with VOLFM and VOLRDS via I²C-bus.

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Product specification



8.1.1 THE REALIZATION OF COMMON MODE INPUT WITH AIC

A high common mode rejection ratio can be created by the use of the ground return pin. Pin CD_(L)_GND can be used in the case that the left and right channel have one ground return line. CD_(L)_GND and CD_R_GND can be used for separated left and right ground return lines. The ground return lines can be connected via the switch GNDC1/2 and GNDRC1/2 (see Fig.4) to the plus input of the second operational amplifier in the signal path. The signal of which a high common mode rejection ratio is required has a signal and a common signal as input. The common signal is connected to the CD_(L)_GND and/or CD_R_GND input. The actual input can be selected with audio input control AIC1/2(1:0).

In Fig.4 the CD input is selected. In this situation both signal lines going to S1/2 in front of the ADC will contain the common mode signal. The ADC itself will suppress this common mode signal with a high rejection ratio. The inputs CD_L and CD_R in this example are connected via an external resistor tap of 82 k Ω and 100 k Ω to be able to handle larger input signals. The 100 k Ω resistors are needed to provide a DC biasing of the operational amplifiers OA1 and OA2. The 1 M Ω resistor provides DC biasing of OA3 and OA4. If no external resistor tap is needed the resistors of 100 k Ω and 1 M Ω still have to provide DC biasing. Only the 82 k Ω resistor can be removed. The impedance level in combination with parasitic capacitance at input CD_L or CD_R determines for a great deal the achievable common rejection ratio.

10 kΩ 10 kΩ to MUX S1/2 82 kΩ CD_L 72 00 LEFT 10 kΩ -11 01 10 MU OA1 OA3 11 100 kΩ AIC1/2(1:0) G CD_(L)_GND 77 LEFT from 1 MO GNDC1/2 CD-player VREFAD 78 analog GNDRC1/2 MIDREF MO CD R GND 14 GROUND ΗĽ RIGHT 10 kΩ 10 kΩ 100 kO to MUX S1/2 82 kΩ CD_R 70 00 RIGHT 10 kΩ 01 10 OA2 OA4 11 MGT460 off-chip on-chip Fig.4 Example of the use of common mode analog input in combination with input resistor tap.

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Car radio Digital Signal Processor (DSP)



8.1.2 REALIZATION OF THE AUXILIARY INPUT WITH VOLUME CONTROL

A differential input with volume control for mixing to the front left or front right of both DAC outputs is provided. The inputs consist of a PHONE and NAV input. Both are accompanied with their ground return lines. After selection of PHONE or NAV the volume can be changed from about +18 to -22.5 dB in 27 steps and mute (MIX output). This signal can be added to the left and/or right front DAC channels.

The output signals of both input circuits can also be switched to ADC1 and/or ADC2, depending on the settings of audio input control 1 (AIC1) and audio input control 2 (AIC2), without volume control (see Fig.3).

8.1.3 REALIZATION OF THE FM INPUT CONTROL

The gain of the circuit has a maximum of 2.26 (7.08 dB). This results in an input level of 368 mV for full-scale, which means 0 dB (full-scale) at the DSP1 input via the stereo decoder (see Fig.6). The gain can be reduced in steps of 1.5 dB. When the gain is set to -3.4 dB the input level becomes 1229 mV for full-scale. This setting accounts for the 200 mV (RMS) input sensitivity at 22.5 kHz sweep and a saturation of the input at 138 kHz sweep.

RDS update: for RDS update the fast access pin SEL_FR must be made HIGH. In that case the FM_RDS signal also goes through the path that was set for FM_MPX. In this situation the signal must be obtained via the FM_RDS input and a noise sample can be retrieved. The input FM_MPX gets high-ohmic. Charging of the coupling capacitor connected to pin FM_MPX is no longer possible.



8.1.4 PINS VDACN1, VDACN2 AND VDACP

These pins are used as negative and positive reference for the ADC1, 2, 3 and the level-ADC. They have to be directly connected to the V_{SSA1} and filtered V_{DDA1} for optimal performance (see Figs 25 and 26).

8.1.5 PIN VREFAD

Via this pin the midref voltage of the ADCs is filtered. This midref voltage is used as half supply voltage reference of the ADCs. External capacitors (connected to V_{SSA1}) prevent crosstalk between switch cap DACs of the ADCs and buffers and improves the power supply rejection ratio of all components. This pin is also used in the application as reference for the inputs TAPE and CD (see Fig.4). The voltage on pin VREFAD is determent by the voltage on pins VDACP and VDACN1 or VDACN2 and is found as:

$$V_{\text{VREFAD}} = \frac{V_{\text{VDACP}} - V_{\text{VDACN1,2}}}{2}$$

8.1.6 SUPPLY OF THE ANALOG INPUTS

The analog input circuit has separate power supply connections to allow maximum filtering. These pins are V_{SSA1} for the analog ground and V_{DDA1} for the analog power supply.

8.2 The signal audio path for input signals CD, TAPE, AUX, PHONE, NAV and AM

The left and right channels are converted and down-sampled by the ADF1_a, ADF1_b. This data stream is converted into a serial format and fed to the DSP1 and DSP2 source selectors. In Figs 7 and 8 the overall and detailed frequency response curves of the analog-to-digital audio decimation path based on a 44.1 kHz sample frequency are shown.



Fig.7 Overall frequency response curve analog-to-digital audio path decimation based on a 44.1 kHz sample frequency.

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8.3 Signal path for level information

For FM weak signal processing, for AM and FM purposes (absolute level and multipath) a level input is implemented (pin LEVEL). In the event of radio reception the clocking of the filters and the level-ADC is based on a 38 kHz sampling frequency. A DC input signal is converted by a bitstream sigma-delta ADC followed by a decimation filter.

The input signal has to be obtained from a radio part. The tuner must deliver the level information of either AM or FM to pin LEVEL.

The input signal for level must be in the range 0 to 3.3 V ($V_{VDACP} - V_{VDACN}$). The 9-bit level-ADC converts this input voltage in steps with a resolution better than at least 14 mV over the 3.3 V range.

The tolerance on the gain is less than 2%. The MSB is always logic 0 to represent a positive level. Input level span can be increased by an external resistor tap. The high input impedance of the level-ADC makes this possible.

The decimation filter reduces in the event of an 38 kHz based clocking regime the bandwidth of the incoming signal to a frequency range of 0 to 29 kHz with a resulting $f_s = 76$ kHz. The response curve is given in Fig.9.

The level information is sub-sampled by the DSP1 to obtain a field strength and a multipath indication. These values are stored in the coefficient or data RAM. Via the l^2C -bus they can be read and used in other microcontroller programs.



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filters. These decimation filters are switched by means of the I²C-bus bit wide narrow in the wide or narrow band position. In the event of FM reception it must be in the narrow position. 0 α (dB) -20

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8.4 Signal path from FM_MPX input to IAC and stereo decoder

The FM_MPX signal is after selection available at one of three ADCs (ADC1, 2 and 3). The multiplex FM signal is converted to the digital domain in ADC1, 2 and 3 through a bitstream ADC. Improved performance for FM stereo can be achieved by means of adapting the noise shaper curve of the ADC to a higher bandwidth.

The first decimation takes place in two down-sample

After selection of one of the ADCs, the FM_MPX path it is followed by the IAC and the FM stereo decoder. One of the two MPX filter outputs contains the multiplex signal with a frequency range of 0 to 60 kHz. The overall low-pass frequency response of the decimation filters is shown in Fig.10.



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The outputs of the stereo decoder to the DSP1, which are all running on a sample frequency of 38 kHz are:

- Pilot presence indication: pilot-I. This 1-bit signal is LOW for a pilot frequency deviation <4 kHz and HIGH for a pilot frequency deviation >4 kHz and locked on a pilot tone.
- 'Left' and 'right' FM reception stereo signal: this is the 18-bit output of the stereo decoder after the matrix decoding.
- Noise level (see also Section 8.4.1): which is retrieved from the high-pass output of the MPX filter. The noise level is detected and filtered in the DSP1 and is used to optimize the FM weak signal processing.

Normally the FM_MPX input and the FM_RDS input have the same source. If the FM input contains a stereo radio channel, the pilot information is switched to the Digitally Controlled Sampling (DCS) clock generation and the DCS clock is locked to the 256×38 kHz of the pilot. In this case this locked frequency is also used for the RDS path ensuring the best possible performance.

Except from the above mentioned theoretical response also the non-flat frequency response of the ADC has to be compensated in the DSP1 program.



8.4.1 NOISE LEVEL

The high-pass 1 (HP1 or narrow band noise level filter) output of the second MPX decimation filter in a band from 60 kHz to 120 kHz is detected with an envelope detector and decimated to a frequency of 38 kHz. The response time of the detector is 100 μ s. Another option is the high-pass 2 (HP2 or wide band noise level filter). This output of the first MPX decimation filter is in a band from 60 to 240 kHz. It has the same properties and is also decimated to the same 38 kHz. Which of the signals is used (HP1 or HP2) is determined by the I²C-bus bit sel_nsdec.

The resulting noise information is rectified and has a word length of 10 bits. This means that the lowest and/or the highest possible level is not used. The noise level can be detected and filtered in the DSP1-core and be used to optimize the FM weak signal processing. The transfer curves of both filters before decimation are shown in Fig.12.



8.4.2 MONO OR STEREO SWITCHING

The DCS block uses a sample rate converter to derive from the XTAL clock, via a PLL, a 512 multiple of 19 kHz (9.728 MHz). In the event of mono reception the DCS circuit generates a preset frequency of n \times 19 kHz ±2 Hz. In the event of stereo reception the frequency is exactly n \times 19 kHz (DCS locked to N \times pilot tone). The detection of the pilot and the stereo indication is done in the DSP program.

8.4.3 THE AUTOMATIC LOCK SYSTEM

The VCO of the DCS block will be at 19 kHz \pm 2 Hz exact based in the event of no-pilot FM_MPX reception or in the event of only RDS reception. In the event of stereo reception the phase error is zero for a pilot tone with a frequency of exactly 19 kHz.

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8.5 DCS clock

In radio mode the stereo decoder, the ADC3 and RDS demodulator, the ADC1 or ADC2 and the level decimation filters have to run synchronously to the 19 kHz pilot. Therefore a clock signal with a controlled frequency of a multiple of 19 kHz (9.728 MHz = 512×19 kHz) is needed.

In the SAA7706H the patented method of non-equidistant digitally controlled sampling DCS clock has been implemented. By a special dividing mechanism a frequency of 9.728 MHz from the PLL2 clock frequency of >40 MHz is generated. The dividing can be changed by means of I²C-bus bits to cope with the different input frequencies of the DCS block.

The DCS system is controlled by up or down information from the stereo decoder. In the event of mono transmissions or 44.1 kHz ADC1 or ADC2 usage the DCS clock is still controlled by the stereo decoder loop. The output keeps the DCS free running on a multiple frequency of 19 kHz \pm 2 Hz if the correct clock setting is applied. In

tape/cd of either 38 or 44.1 kHz and AM mode the DCS clock always has to be put in preset mode with a bit in the I^2C -bus memory map definitions.

8.6 The Interference Absorption Circuit (IAC)

8.6.1 GENERAL DESCRIPTION

The IAC detects and suppresses ignition interference. This hardware IAC is a modified, digitized and extended version of the analog circuit which is in use for many years already.

The IAC consists of an MPX mute function switched by mute pulses from ignition interference pulse detectors. The input signal of a second IAC detection circuit is the FM level signal (the output of the level-ADC). This detector performs optimally in lower antenna voltage circumstances. It is therefore complementary to the first detector.

The input signal of a first IAC detection circuit is the output signal of one of the down-sample paths coming from ADC1 or ADC2. This interference detector analyses the high-frequency contents of the MPX signal. The discrimination between interference pulses and other signals is performed by a special Philips patented fuzzy logic such as algorithm and is based on probability calculations. This detector performs optimally in higher antenna voltage circumstances. On detection of ignition interference, this logic will send appropriate pulses to the MPX mute switch. The characteristics of both IAC detectors can be adapted to the properties of different FM front-ends by means of the predefined coefficients in the IAC control registers. The values can be changed via the I²C-bus. Both IAC detectors can be switched on or off independently of each other. Both IAC detectors can mute the MPX signal independently of each other.

A third IAC function is the dynamic IAC circuit. This block is intended to switch off the IAC completely the moment the MPX signal has a too high frequency deviation which in the event of small IF filters can result in AM modulation. This AM modulation could be interpreted by the IAC circuitry as interference caused by the car's engine.

8.7 The Filter Stream DAC (FSDAC)

The FSDAC is a semi-digital reconstruction filter that converts the 1-bit data stream of the noise shaper to an analog output voltage. The filter coefficients are implemented as current sources and are summed at virtual ground of the output operational amplifier. In this way very high signal-to-noise performance and low clock jitter sensitivity is achieved. A post-filter is not needed due to the inherent filter function of the DAC. On-board amplifiers convert the FSDAC output current to an output voltage signal capable of driving a line output.

The output voltage of the FSDAC scales proportionally with the power supply voltage.

8.7.1 INTERPOLATION FILTER

The digital filter interpolates from 1 to $64f_s$ by means of a cascade of a recursive filter and an FIR filter.

ITEM	CONDITIONS	VALUE (dB)
Pass band ripple	$0 - 0.45 f_{s}$	±0.03
Stop band	>0.55f _s	-50
Dynamic range	$0 - 0.45 f_{s}$	116.5
Gain	DC	-3.5

Table 2 Digital interpolation filter characteristics

8.7.2 NOISE SHAPER

The 5th-order noise shaper operates at $64f_s$. It shifts in-band quantization noise to frequencies well above the audio band. This noise shaping technique enables high signal-to-noise ratios to be achieved. The noise shaper output is converted into an analog signal using a filter stream digital-to-analog converter.

8.7.3 FUNCTION OF PIN POM

With pin POM it is possible to switch off the reference current of the DAC. The capacitor on pin POM determines the time after which this current has a soft switch-on. So at power-on the current audio signal outputs are always muted. The loading of the external capacitor is done in two stages via two different current sources. The loading starts at a current level that is lower than the current loading after the voltage on pin POM has past a particular level. This results in an almost dB-linear behaviour. This must prevent 'plop' effects during power on or off.

8.7.4 POWER-OFF PLOP SUPPRESSION

To avoid plops in a power amplifier, the supply voltage of the analog part of the DAC and the rest of the chip can be fed from a separate power supply of 3.3 V. A capacitor connected to this power supply enables to provide power to the analog part at the moment the digital voltage is switching off fast. In this event the output voltage will decrease gradually allowing the power amplifier some extra time to switch off without audible plops.

8.7.5 PIN VREFDA FOR INTERNAL REFERENCE

With two internal resistors half the supply voltage V_{DDA2} is obtained and used as an internal reference. This reference voltage is used as DC voltage for the output operational amplifiers and as reference for the DAC.

In order to obtain the lowest noise and to have the best ripple rejection, a filter capacitor has to be added between this pin and ground, preferably close to the analog pin V_{SSA2} .

8.7.6 SUPPLY OF THE FILTER STREAM DAC

The entire analog circuitry of the DACs and the operational amplifiers are supplied by 2 supply pins: V_{DDA2} and V_{SSA2} . V_{DDA2} must have sufficient decoupling to prevent total harmonic distortion degradation and to ensure a good power supply rejection ratio. The digital part of the DAC is fully supplied from the chip core supply.

8.8 Clock circuit and oscillator

The chip has an on-chip crystal clock oscillator. The block diagram of this Pierce oscillator is shown in Fig.13. The active element needed to compensate for the loss resistance of the crystal is the block G_m . This block is placed between the external pins OSC_IN and OSC_OUT. The gain of the oscillator is internally controlled by the AGC block. A sine wave with a peak-to-peak voltage close to the oscillator power supply voltage is generated. The AGC block prevents clipping of the sine wave and therefore the higher harmonics are as low as possible. At the same time the voltage of the sine wave is as high as possible which reduces the jitter going from sine wave to the clock signal.



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8.8.1 SUPPLY OF THE CRYSTAL OSCILLATOR

The power supply connections of the oscillator are separated from the other supply lines. This is done to minimize the feedback from the ground bounce of the chip to the oscillator circuit. Pin $V_{SS(OSC)}$ is used as ground supply and pin $V_{DD(OSC)}$ as positive supply. A series resistor plus capacitance is required for proper operating on pin $V_{DD(OSC)}$, see Figs 25 and 26. See also important remark in Section 8.10.

8.9 The phase-locked loop circuit to generate the DSPs and other clocks

There are several reasons why a PLL circuit is used to generate the clock for the DSPs:

- The PLL makes it possible to switch in the rare cases that tuning on a multiple of the DSP clock frequency occurs to a slightly higher frequency for the clock of the DSP. In this way an undisturbed reception with respect to the DSP clock frequency is possible.
- Crystals for the crystal oscillator in the range of twice the required DSP clock frequency, so approximately 100 MHz, are always third overtone crystals and must also be manufactured on customer demand. This makes these crystals expensive. The PLL1 enables the use of a crystal running in the fundamental mode and also a general available crystal can be chosen. For this circuit a 256 × 44.1 kHz = 11.2896 MHz crystal is chosen. This type of crystal is widely used.

 Although a multiple of the frequency of the used crystal of 11.2896 MHz falls within the FM reception band, this will not disturb the reception because the relatively low frequency crystal is driven in a controlled way and the sine wave of the crystal has in the FM reception band only very minor harmonics.

8.10 Supply of the digital part (V_{DDD3V1} to V_{DDD3V4})

The supply voltage on pins V_{DDD3V1} to V_{DDD3V4} must be for at least 10 ms earlier active than the supply voltage applied to pin $V_{DD(OSC)}$.

8.11 CL_GEN, audio clock recovery block

When an external I²S-bus or SPDIF source is connected, the FSDAC circuitry needs an $256f_s$ related clock. This clock is recovered from either the incoming WS of the digital serial input or the WS derived from the SPDIF1/SPDIF2 input. There is also a possibility to provide the chip with an external clock, in that case it must be a 256f_s clock with a fixed phase relation to the source.

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8.12 External control pins

8.12.1 DSP1

For external control two input pins have been implemented. The status of these pins can be changed by applying a logic level. The status is saved in the DSP1 status register. The function of each pin depends on the DSP1 program.

To control external devices two output pins are implemented. The status of these pins is controlled by the DSP program.

Function of these 'control pins' can be found in a separate manual and is rom_code dependent.

8.12.2 DSP2

For external control four configurable I/O pins have been implemented. Via the I²C-bus these four pins can be independently configured as input or output. The status of these pins can be changed by applying a logic level (input mode). The status is saved in the DSP2 status register. The function of each pin depends on the I²C-bus setting and DSP2 program.

Function of these 'control pins' can be found in a separate manual and is rom_code dependent.

8.13 I²C-bus control (pins SCL and SDA)

General information about the I^2 C-bus can be found in *"The I²C-bus and how to use it"*. This document can be ordered using the code 9398 393 40011. For the external control of the SAA7706H device a fast I²C-bus is implemented. This is a 400 kHz bus which is downward-compatible with the standard 100 kHz bus. There are two different types of control instructions:

- Instructions to control the DSP program, programming the coefficient RAM and reading the values of parameters (level, multipath etc.)
- Instructions controlling the data flow; such as source selection, IAC control and clock speed.

The detailed description of the I²C-bus and the description of the different bits in the memory map is given in Chapter 9.

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8.14 Digital serial inputs/outputs and SPDIF inputs

8.14.1 GENERAL DESCRIPTION DIGITAL SERIAL AUDIO INPUTS/OUTPUTS

For communication with external digital sources a digital serial bus is implemented. It is a serial 3-line bus, having one line for data, one line for clock and one line for the word select. For external digital sources the SAA7706H acts as a slave, so the external source is master and supplies the clock.

The digital serial input is capable of handling multiple input formats. The input is capable of handling Philips I²S-bus and LSB-justified formats of 16, 18, 20 and 24 bits word sizes. The sampling frequency can be either 44.1 or 48 kHz. See Fig.15 for the general waveform formats of all possible formats.

The number of bit clock (BCK) pulses may vary in the application. When the applied word length is smaller than 24 bits (internal resolution of DSP2), the LSB bits will get internally a zero value; when the applied word length exceeds 24 bits then the LSBs are skipped.

It should be noted that:

- Two digital sources can not be used at the same time
- Maximum number of bit clocks per word select (WS) is limited to 64
- The word select (WS) must have a duty cycle of 50%.
- 8.14.2 GENERAL DESCRIPTION SPDIF INPUTS (SPDIF1 AND SPDIF2)

For communication with external digital sources also an SPDIF input can be used. The two SPDIF input pins can be connected via an analog multiplexer to the SPDIF receiver. It is a receiver without an analog PLL that samples the incoming SPDIF with a high frequency. In this way the data is recovered synchronously on the applied system clock.

From the SPDIF signal a three wire serial bus (e.g. I^2S -bus) is made, consisting of a word select, data and bit clock line. The sample frequency f_s depends solely on the SPDIF signal input accuracy and both 44.1 and 48 kHz are supported. This chip does not handle the user data bits, channel status bits and validity bits of the SPDIF stream, but only the audio is given at its outputs. Some rom_codes do take care of the pre-emphasis bit of the SPDIF stream.

The bits in the audio space are always decoded regardless of any status bits e.g. 'copy protected', 'professional mode' or 'data mode'. The DAC is not muted in the event of a non-linear PCM audio, however the bit is observable via the l²C-bus. A few other channel status bits are available. There are 5 control signals available from the SPDIF input stage. These are connected to flags of DSP2. For more details see separate manual.

These 5 control signals are:

- Signals to indicate the sample frequency of the SPDIF signal: 44.1 and 48 kHz (32 kHz is not supported)
- A lock signal indicating if the SPDIF input is in lock
- The pre-emphasis bit of the SPDIF audio stream
- The pcm_audio/non-pcm_audio bit indicating if an audio or data stream is detected. The FSDAC output will not be muted in the event of a non-audio PCM stream. This status bit can be read via the I²C-bus, the microcontroller can decide to mute the DAC (via pin POM).

The design fulfils the digital audio interface specification *"IEC 60958-1 Ed2, part 1, general part IEC 60958-3 Ed2, part 3, consumer applications"*.

It should be noted that:

- The SPDIF input may only be used in the 'consumer mode' specified in the digital audio interface specification
- Only one of the two SPDIF sources can be used (selected) at the same time
- The FSDAC will not (automatically) be muted in the event of a non-audio stream
- Two digital sources can not be used at the same time
- Supported sample frequencies are 44.1 and 48 kHz.



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The RDS demodulator recovers the additional inaudible RDS information which is transmitted by FM radio broadcasting. The (buffered) data is provided as output for further processing by a suitable decoder. The operational functions of the decoder are in accordance with the EBU specification *"EN 50067"*.

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The RDS demodulator has three different functions:

- Clock and data recovery from the MPX signal
- Buffering of 16 bits, if selected
- Interfacing with the microcontroller.

8.15.1 CLOCK AND DATA RECOVERY

The RDS-chain has a separate input. This enables RDS updates during tape play and also the use of a second receiver for monitoring the RDS information of signals from an other transmitter (double tuner concept). It can as such be done without interruption of the audio program. The MPX signal from the main tuner of the car radio can be connected to this RDS input via the built-in source selector. The input selection is controlled by an I²C-bus bit.

The RDS chain contains a sigma-delta ADC (ADC3), followed by two decimation filters. The first filter passes the multiplex band including the signals around 57 kHz and reduces the sigma-delta noise. The second filter reduces the RDS bandwidth around 57 kHz. The overall filter curve is shown in Fig.16 and a more detailed curve of the RDS 57 kHz band in Fig.17.



Fig.16 Overall frequency response curve decimation filters.



The quadrature mixer converts the RDS band to the frequency spectrum around 0 Hz and contains the appropriate Q/I signal filters. The final decoder with CORDIC recovers the clock and data signals. These signals are output on pins RDS_CLOCK and RDS_DATA. In the event of FM-stereo reception the clock of the total chip is locked to the stereo pilot (19 kHz multiple). In the event of FM-mono the DCS loop keeps the DCS clock around the same 19 kHz multiple. In all other cases like AM reception or tape, the DCS circuit has to be set in a preset position by means of an I²C-bus bit. Under these conditions the RDS system is always clocked by the DCS clock in a 38 kHz (4 × 9.5 kHz) based sequence.

8.15.2 TIMING OF CLOCK AND DATA SIGNALS

The timing of the clock and data output is derived from the incoming data signal. Under stable conditions the data will remain valid for 400 μ s after the clock transition. The timing of the data change is 100 μ s before a positive clock change. This timing is suited for positive as well as negative triggered interrupts on a microcontroller. The RDS timing is shown in Fig.18. During poor reception it is possible that faults in phase occur, then the duty cycle of the clock and data signals will vary from minimum 0.5 times to a maximum of 1.5 times the standard clock periods. Normally, faults in phase do not occur on a cyclic basis.

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8.15.3 BUFFERING OF RDS DATA

The repetition of the RDS data is around the 1187 Hz. This results in an interrupt on the microcontroller for every 842 μ s. In a second mode, the RDS interface has a double 16-bit buffer.

8.15.4 BUFFER INTERFACE

The RDS interface buffers 16 data bits. Every time 16 bits are received, the data line is pulled down and the buffer is overwritten. The microcontroller has to monitor the data line in at most every 13.5 ms. This mode can be selected via an l^2 C-bus.

In Fig.19 the interface signals from the RDS decoder and the microcontroller in buffer mode are shown. When the buffer is filled with 16 bits the data line is pulled down. The data line will remain LOW until reading of the buffer is started by pulling down the clock line. The first bit is clocked out. After 16 clock pulses the reading of the buffer is ready and the data line is set HIGH until the buffer is filled again. The microcontroller stops communication by pulling the line HIGH. The data is written out just after the clock HIGH-to-LOW transition. The data is valid when the clock is HIGH. When a new 16-bit buffer is filled before the other buffer is read, that buffer will be overwritten and the old data is lost.

RDS_DATA D0 D1 D2 D13 D14 D15 D15 RDS_CLOCK two start reading data MGU271

Fig.19 Interface signals RDS decoder and microcontroller (buffer mode).

8.16 DSP reset

Pin DSP_RESET is active LOW and requires an external pull-up resistor. Between this pin and the V_{SSD} ground a capacitor should be connected to allow a proper switch-on of the supply voltage. The capacitor value is such that the chip is in reset as long as the power supply is not stabilized. A more or less fixed relationship between the DSP_RESET (pin) and the POM (pin) time constant is mandatory.

The voltage on pin POM determines the current flowing in the DACs. At 0 V on pin POM the DAC currents are zero and so are the DAC output voltages.

At the V_{DDA2} voltage the DAC currents are at their nominal (maximal) value. Long before the DAC outputs get to their nominal output voltages, the DSP must be in working mode to reset the output register: therefore the DSP time constant must be shorter than the POM time constant. For recommended capacitors see Figs 25 and 26.

The reset has the following function:

- All I²C-bus bits are set to their default value
- The DSP status registers (DSP1 and DSP2) are reset

- The program counter of both DSPs are set to address 0000H
- The two output flags of DSP1 (DSP1_OUT1 and DSP1_OUT2) are reset to logic 0. All the configurable flags of DSP2 are reset to logic 0, however the four flags available at the output of the chip are default configured as input flags (DSP2_INOUT1, DSP2_INOUT2, DSP2_INOUT3 and DSP2_INOUT4).

When the level on pin DSP_RESET is at HIGH, the DSP program (DSP1 and DSP2) starts to run.

8.17 Test mode connections (pins TSCAN, RTCB and SHTCB)

Pins TSCAN, RTCB and SHTCB are used to put the chip in test mode and to test the internal connections. Each pin has an internal pull-down resistor to ground. In the application these pins can be left open or connected to ground.

9 I²C-BUS FORMAT

For more general information on the I^2C -bus protocol, see the Philips I^2C -bus specification.

9.1 Addressing

Before any data is transmitted on the I²C-bus, the device which should respond is addressed first. The addressing is always done with the first byte transmitted after the start procedure.

9.2 Slave address (pin A0)

The SAA7706H acts as slave receiver or a slave transmitter. Therefore the clock signal SCL is only an input signal. The data signal SDA is a bidirectional line. The SAA7706H slave address is shown in Table 3.

Table 3 Slave address

MSB							LSB
0	0	1	1	1	0	A0	R/W

The sub-address bit A0 corresponds to the hardware address pin A0 which allows the device to have 2 different addresses. The A0 input is also used in test mode as a serial input of the test control block.

9.3 Write cycles

The I²C-bus configuration for a write cycle is shown in Fig.20. The write cycle is used to write the bytes to both DSP1 and DSP2 for manipulating the data and coefficients. Depending on which DSP is accessed the data protocol exists out of 2, 3 or 4 bytes. More details can be found in the I²C-bus memory map (see Table 5).

The data length is 2, 3 or 4 bytes depending on the accessed memory. If the Y-memory of DSP1 is addressed the data length is 2 bytes, in the event of the X-memory of DSP1 or X/Y-memory of DSP2 the length is 3 bytes. The slave receiver detects the address and adjusts the number of bytes accordingly. The data length of 4 bytes is not used in the SAA7706H.

9.4 Read cycles

The I²C-bus configuration for a READ cycle is shown in Fig.21. The read cycle is used to read the data values from XRAM or YRAM of both DSPs. The master starts with a START condition S, the SAA7706H address '0011100' and a logic 0 (write) for the R/\overline{W} bit. This is followed by an acknowledge of the SAA7706H.

Then the master writes the high memory address and low memory address where the reading of the memory content of the SAA7706H must start. The SAA7706H acknowledges these addresses both. Then the master generates a repeated START (Sr) and again the SAA7706H address '0011100' but this time followed by a logic 1 (read) of the R/W bit.

From this moment on the SAA7706H will send the memory content in groups of 2 (Y-memory DSP1) or 3 (X-memory DSP1, X/Y-memory DSP2 or registers) bytes to the I²C-bus each time acknowledged by the master. The master stops this cycle by generating a negative acknowledge, then the SAA7706H frees the I²C-bus and the master can generate a STOP condition. The data is transferred from the DSP register to the I²C-bus register at execution of the MPI instruction in the DSP2 program. Therefore at least once every DSP routine an MPI instruction should be added. The data length of 4 bytes is not used in the SAA7706H.

9.5 SAA7706H hardware registers

The write cycle can be used to write the bytes to the hardware registers to control the DCS block, the PLL for the DSP clock generation, the IAC settings, the AD volume control settings, the analog input selection, the format of the I²S-bus and some other settings. It is also possible to read these locations for chip status information. More detail can be found in the I²C-bus memory map, Tables 4 and 5.

9.5.1 SAA7706H DSPs REGISTERS

The hardware registers have two different address blocks. One block exists out of hardware register locations which control both DSPs and some major settings such as the PLL division. These locations have a maximum of 16 bits, which means 2 bytes need to be sent to or read from. For the SAA7706H one register is located at the DSPs and general control register (0FFFH).

The second block has an address space of 16 addresses and are all X-memory mapped on DSP2. While this space is 24 bits wide 3 bytes should be sent to or read from. These addresses are DSP2 mapped which means an MPI instruction is needed for accessing those locations and there is no verifying mechanism if all addresses are really mapped to physical registers. Therefore, all those locations will be acknowledged even if the data is not valid. For the SAA7706H several registers are located in this section. A few registers are predefined for DSP2 purposes (see Table 5).



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9.6 I²C-bus memory map specification

The I²C-bus memory map contains all defined I²C-bus bits. The map is split up in two different sections, the hardware memory registers and the RAM definitions. In Table 5 the preliminary memory map is depicted. The hardware registers are memory map on the XRAM of DSP2. Table 5 shows the detailed memory map of those locations. All locations are acknowledged by the SAA7706H even if the user tries to write to a reserved space. The data in these sections will be lost. Reading from this locations will result in undefined data words.

Table 4I²C-bus memory map

ADDRESS	FUNCTION	SIZE
2000H to 21FFH	YRAM (DSP2)	512×12 bits
1FF0H to 1FFFH	hardware registers	16×24 bits
1000H to 127FH	XRAM (DSP2)	640×24 bits
0FFFH	DSP CONTROL	1×16 bits
0800H to 097FH	YRAM (DSP1)	384×12 bits
0000H to 017FH	XRAM (DSP1)	384×18 bits

Table 5 I²C-bus memory map overview of hardware registers

DESCRIPTION	REGISTER
Hardware registers	
Program counter register DSP2	1FFFH
Status register DSP2	1FFEH
I/O configuration register DSP2	1FFDH
Phone, navigation and audio register	1FFCH
FM and RDS sensitivity register	1FFBH
Clock coefficient register	1FFAH
Clock settings register	1FF9H
IAC settings register	1FF8H
Selector register	1FF7H
CL_GEN register 4	1FF6H
CL_GEN register 3	1FF5H
CL_GEN register 2	1FF4H
CL_GEN register 1	1FF3H
Evaluation register	1FF0H
DSP control	·
DSPs and general control register	OFFFH

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10 LIMITING VALUES

In accordance with the Absolute Maximum Ratings System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{DD}	supply voltage		-0.5	+3.6	V
V _n	input voltage on any pin		-0.5	+5.5	V
I _{IK}	DC input clamping diode current	$V_{I} < -0.5 \text{ V or } V_{I} > V_{DD} + 0.5 \text{ V}$	-	±10	mA
I _{OK}	DC output clamping diode current	$V_{O} < -0.5$ V or $V_{O} > V_{DD} + 0.5$ V	-	±20	mA
I _{O(sink/source)}	DC output source or sink current	$-0.5 \text{ V} < \text{V}_{\text{O}} < \text{V}_{\text{DD}} + 0.5 \text{ V}$	-	±20	mA
I _{DD} ,I _{SS}	supply current per supply pin		-	±50	mA
T _{amb}	ambient operating temperature		-40	+85	°C
T _{stg}	storage temperature range		-65	+125	°C
V _{ESD}	ESD voltage				
	human body model	100 pF; 1500 Ω	2000	_	V
	machine model	200 pF; 0.5 μH; 10 Ω	200	_	V
I _{lu(prot)}	latch-up protection current	CIC spec/test method	100	-	mA
P _{tot}	total power dissipation		-	890	mW

11 THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-a)}	thermal resistance from junction to ambient	mounted on printed-circuit board	45	K/W

12 CHARACTERISTICS

 V_{DD} = 3 to 3.6 V; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Supplies; T _{am}	_b = −40 to +85 °C					•
V _{DD}	operating supply voltage	all V_{DD} pins with respect to V_{SS}	3.0	3.3	3.6	V
I _{DDD}	supply current of the digital part	DSP1 at 50 MHz; DSP2 at 62.9 MHz	-	110	150	mA
I _{DDD(core)}	supply current of the digital core part	DSP1 at 50 MHz; DSP2 at 62.9 MHz	-	105	140	mA
I _{DDD(peri)}	supply current of the digital periphery part	without external load to ground	-	5	10	mA
I _{DDA}	supply current of the analog part	zero input and output signal	-	40	60	mA
I _{DDA(ADC)}	supply current of the ADCs	zero input and output signal	-	15	26	mA
I _{DDA(DAC)}	supply current of the DACs	zero input and output signal	-	19	30	mA
I _{DDA(osc)}	supply current XTAL oscillator	functional mode	-	2	4	mA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	
P _{tot}	total power dissipation	DSP1 at 50 MHz, DSP2 at 62.9 MHz	_	540	750	mW
Digital I/O; T _{am}	$_{\rm nb}$ = -40 to +85 °C; V _{DD} = 3 t	to 3.6 V				
V _{IH}	HIGH-level input voltage for all digital inputs and I/Os		2.0	_	-	V
VIL	LOW-level input voltage for all digital inputs and I/Os		_	_	0.8	V
V _{hys}	Schmitt trigger hysteresis voltage		0.4	-	-	V
V _{OH}	HIGH-level output voltage	standard output; I _O = -4 mA	V _{DD} - 0.4	-	-	V
		5 ns slew rate output; $I_0 = -4 \text{ mA}$	V _{DD} - 0.4	-	-	V
		10 ns slew rate output; $I_0 = -2 \text{ mA}$	V _{DD} - 0.4	-	-	V
		20 ns slew rate output; $I_0 = -1 \text{ mA}$	$V_{DD} - 0.4$	-	-	V
V _{OL}	LOW-level output voltage	standard output; I _O = 4 mA	_	_	0.4	V
		5 ns slew rate output; I _O = 4mA	-	-	0.4	V
		10 ns slew rate output; I _O = 2 mA	_	-	0.4	V
		20 ns slew rate output; I _O = 1 mA	-	-	0.4	V
		I ² C-bus output; I _O = 4 mA	-	-	0.4	V
I _{LO}	output leakage current 3-state outputs	$V_{O} = 0 V \text{ or } V_{DD}$	-	-	±5	μA
R _{pd}	internal pull-down resistor to $V_{\mbox{\scriptsize SS}}$		24	50	140	kΩ
R _{pu}	internal pull-up resistor to V _{DD}		30	50	100	kΩ
C _i	input capacitance		-	-	3.5	pF
t _{i(r)} ,t _{i(f)}	input rise and fall times	V _{DD} = 3.6 V	-	6	200	ns
t _{o(t)}	output transition time	standard output; $C_L = 30 \text{ pF}$	-	3.5	-	ns
		5 ns slew rate output; $C_L = 30 \text{ pF}$	-	5	-	ns
		10 ns slew rate output; $C_L = 30 \text{ pF}$	_	10	-	ns
		20 ns slew rate output; $C_L = 30 \text{ pF}$	-	20	-	ns
		I^2C -bus output; $C_b = 400 \text{ pF}$	60	-	300	ns

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Analog inputs	; T _{amb} = 25 °C; V _{DDA1} = 3.3 V	V	•	-			
DC CHARACTER	STICS						
$\frac{V_{VREFAD}}{V_{VDDA1}}$	common mode reference voltage ADC1, ADC2 and level-ADC	with reference to V_{SSA1}	0.47	0.50	0.53		
Z _{o(VREFAD)}	output impedance at pin VREFAD		-	10	-	Ω	
V _{VDACP}	positive reference voltage ADC1, 2, 3 and level-ADC		3	3.3	3.6	V	
I _{VDACP}	positive reference current ADC1, 2, 3 and level-ADC		-	-200	-	μA	
V _{VDACN1} , V _{VDACN2}	negative reference voltage ADC1, 2, 3 and level-ADC		-0.3	0	+0.3	V	
I _{VDACN1} , I _{VDACN2}	negative reference current ADC1, 2 and 3		-	200	-	μA	
V _{IO(ADC)}	input offset voltage ADC1, 2 and 3		-	140	-	mV	
AC CHARACTERI	STICS						
V _{i(con)(max)(rms)}	maximum conversion input level (RMS value)						
	CD, TAPE, AM and AUX input signals	THD <1%	0.6	0.66	-	V	
	FM_MPX input signal	THD <1%; VOLFM = 00H	0.33	0.368	_	V	
R _i	input impedance CD, TAPE, AM and AUX input signals		1	-	_	MΩ	
	FM_MPX input signal		48	60	72	kΩ	
THD	total harmonic distortion						
	CD, TAPE, AM and AUX input signals	input signal 0.55 V (RMS) at 1 kHz; bandwidth = 20 kHz; f _s = 44.1 kHz	-	-85	-75	dB	
	FM_MPX input signal	input signal 368 mV (RMS) at 1 kHz; bandwidth = 19 kHz; VOLFM = 00H	-	-70 0.03	-65 0.056	dB %	
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT	
-----------------------------	---	--	------	------	------	------	--
S/N	signal-to-noise ratio						
	CD, TAPE, AM and AUX input signals	input signal at 1 kHz; bandwidth = 20 kHz; 0 dB reference = 0.55 V (RMS); f _s = 44.1 kHz	85	90	-	dB	
	FM_MPX input signal mono	input signal at 1 kHz; bandwidth = 19 kHz; 0 dB reference = 0.368 V (RMS); VOLFM = 00H	80	83	-	dB	
	FM_MPX input signal stereo	input signal at 1 kHz; bandwidth = 40 kHz; 0 dB reference = 0.368 V (RMS); VOLFM = 00H	75	81	-	dB	
α ₁₉	carrier and harmonic suppression at the output	pilot signal frequency = 19 kHz	_	81	-	dB	
		unmodulated	_	98	_	dB	
α ₃₈	carrier and harmonic suppression at the output	subcarrier frequency = 38 kHz	-	83	_	dB	
		unmodulated	-	91	—	dB	
α ₅₇	carrier and harmonic suppression for 19 kHz,	subcarrier frequency = 57 kHz	-	83	-	dB	
	including notch	unmodulated	-	96	-	dB	
α ₇₆	carrier and harmonic suppression for 19 kHz,	subcarrier frequency = 76 kHz	-	84	-	dB	
	including notch	unmodulated	-	94	-	dB	
IM _{α10}	intermodulation	f _{mod} = 10 kHz; f _{spur} = 1 kHz	77	-	-	dB	
$IM_{\alpha 13}$	intermodulation	f _{mod} = 13 kHz; f _{spur} = 1 kHz	76	-	—	dB	
α _{57(VF)}	traffic radio suppression	f = 57 kHz	-	110	-	dB	
α _{67(SCA)}	Subsidiary Communication Authority (SCA) suppression	f = 67 kHz	-	110	-	dB	
α ₁₁₄	adjacent channel suppression	f = 114 kHz	_	110	-	dB	
α ₁₉₀	adjacent channel suppression	f = 190 kHz	-	110	-	dB	
V _{th(pilot)(rms)}	pilot threshold voltage	stereo on; VOLFM = 07H	-	35.5	—	mV	
	(RMS value) at pin DSP1_OUT1	stereo off; VOLFM = 07H	-	35.4	-	mV	
hys	hysteresis of V _{th(pilot)(rms)}		-	0	_	dB	
α _{cs1}	channel separation	f _i = 1 kHz	40	45	-	dB	
	FM-stereo input	f _i = 10 kHz	25	30	-	dB	
α_{cs2}	channel separation CD, TAPE, AM and AUX input signals		60	70	-	dB	

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
f _{res}	audio frequency response					
	CD, TAPE, AM and AUX input signals	f _s = 44.1 kHz; at −3 dB	20	_	-	kHz
	FM_MPX input signal	at –3 dB via DSP at DAC output	17	-	-	kHz
ΔG_{L-R}	overall left/right gain unbalance (TAPE, CD, AUX and AM input signals)		-	-	0.5	dB
α_{ct}	crosstalk between inputs	f _i = 1 kHz	65	_	-	dB
		f _i = 15 kHz	50	_	_	dB
PSRR _{MPX/RDS}	power supply ripple rejection MPX and RDS ADCs	output via I ² S-bus; ADC input short-circuited; f _{ripple} = 1 kHz; $V_{ripple} = 100 \text{ mV} \text{ (peak)};$ $C_{VREFAD} = 22 \mu\text{F};$ $C_{VDACP} = 10 \mu\text{F}$	35	45	_	dB
PSRR _{LAD}	power supply ripple rejection level-ADC	output via DAC; ADC input short-circuited; $f_{ripple} = 1 \text{ kHz}$; $V_{ripple} = 100 \text{ mV} \text{ (peak)}$; $C_{VREFAD} = 22 \mu\text{F}$	29	39	_	dB
CMRR _{CD}	common-mode rejection ratio for CD input mode	$\begin{split} R_{CD_{(L)}_{GND}} &= 1 \ M\Omega; \\ \text{resistance of CD player} \\ \text{ground cable < 1 } k\Omega; \\ f_i &= 1 \ \text{kHz} \end{split}$	60	_	-	dB
AC characteris	tics PHONE and NAV inpu	ts; T _{amb} = 25 °C; V _{DDA1} = 3.3 V	1			
THD	total harmonic distortion of PHONE and NAV input signals at maximum input voltage	$\label{eq:Vi} \begin{array}{l} V_i = 0.75 \; V \; (RMS); f_i = 1 \; kHz; \\ VOLMIX = 30H; \; measured \; at \\ FLV \; and \; FRV \; outputs \end{array}$	40	-	_	dB
CMRR	common mode rejection ratio of PHONE and NAV input signals	$\label{eq:Vi} \begin{array}{l} V_i = 0.75 \; V(RMS); \\ f_i = 1 \; \; kHz; \\ VOLMIX = 30 H \end{array}$	25	50	-	dB
R _i	input impedance of PHONE, NAV/AM_L and AM_R input signals		90	120	150	kΩ
V _{i(max)(rms)}	maximum input level of PHONE and NAV input signals (RMS value)	f _i = 1 kHz; VOLMIX = 30H	0.75	1	-	V
AC characteris	tics FM_RDS input; T _{amb} =	25 °C; V _{DDA1} = 3.3 V				
Vi(con)(max)(rms)	maximum conversion level of FM_RDS input (RMS value)	naximum conversion level THD < 1%; VOLRDS = 00H 0.33 0.368 f FM_RDS input		-	V	
R _{i(FM_RDS)}	input resistance FM_RDS input		40	60	72	kΩ
THD _{FM_RDS}	total harmonic distortion RDS ADC	f _c = 57 kHz	-60	-67	-	dB

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	
S/N _{FMRDS}	signal-to-noise ratio RDS ADC	6 kHz bandwidth; $f_c = 57$ kHz; 0 dB reference = 0.55 V (RMS); VOLRDS = 00H	54	-	-	dB
α_{pilot}	pilot attenuation RDS		50	-	_	dB
α	nearby selectivity RDS	neighbouring channel at 200 kHz distance	61	_	-	dB
$\alpha_{n(ADC)}$	RDS ADC noise attenuation		70	-	-	dB
V _{ripple(RDS)}	ripple voltage RDS pass band	2.4 kHz bandwidth	-	_	0.5	dB
$\alpha_{mux(RDS)}$	multiplex attenuation RDS	mono	70	-	_	dB
		stereo	40	-	_	dB
Δf_{osc}	allowable frequency deviation of the 57 kHz RDS	maximum crystal resonance frequency deviation of 100 ppm	-	-	6	Hz
AC characteri	stics SPDIF1 and SPDIF2 in	puts; T _{amb} = 25 °C; V _{DDA2} = 3.	.3 V		•	•
V _{i(p-p)}	AC input level (peak-to-peak level)		0.2	0.5	3.3	V
R _i	input impedance	at 1 kHz	_	6	_	kΩ
V _{hys} hysteresis of input voltage			_	40	_	mV
AC characteri	stics analog LEVEL input; 1	Γ _{amb} = 25 °C; V _{DDA1} = 3.3 V				
S/N _{LAD}	signal-to-noise ratio of level-ADC	0 to 29 kHz bandwidth; maximum input level; unweighted	48	54	_	dB
R _i	input resistance		1.0	_	2.2	MΩ
V _{i(fs)(LAD)}	full-scale level-ADC input voltage		0	_	V _{DDA1}	V
V _{IO}	DC offset voltage		_	_	120	mV
α	decimation filter attenuation		20	_	-	dB decade
f _{co(PB)}	pass band cut-off frequency	at –3 dB and DCS clock = 9.728 MHz	-	29	-	kHz
f _{sr}	sample rate frequency after decimation	DCS clock = 9.728 MHz	-	38	-	kHz
Analog DAC o f _i = 1 kHz	utputs on pins FLV, FRV, RI	LV and RRV; T _{amb} = 25 °C; V _{DD}	_{DA2} = 3.3 V	; f _s = 44.1	kHz; R _L =	5 k Ω;
DC CHARACTER	ISTICS					
R _{o(ref)}	reference output resistance	pin VREFDA	-	14	-	kΩ
R _o	DAC output resistance	pins FLV, FRV, RLV and RRV	-	0.13	3.0	Ω
I _{o(max)}	maximum output current	(THD + N)/S < 0.1%; R _L = 5 kΩ	-	0.22	-	mA
RL	load resistance		3	_	_	kΩ

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SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	
CL	load capacitance		_	_	200	pF
AC CHARACTER	ISTICS	•				
V _{o(RMS)}	output voltage (RMS value)		_	1000	-	mV
ΔV _o	unbalance between channels		_	0.1	-	dB
(THD + N)/S	total harmonic	at 0 dB	_	-90	-85	dB
	distortion-plus-noise to signal ratio (measured with system one)	at –60 dB; A-weighted	_	-37	-	dB
S/N	signal-to-noise ratio (measured with system one)	code = 0; A-weighted	_	105	-	dB
α _{cs}	channel separation		-	80	-	dB
PSRR	power supply rejection ratio	$f_{ripple} = 1 \text{ kHz}; V_{ripple(p-p)} = 1\%$	_	50	-	dB
Oscillator; T _{an}	_{nb} = 25 °C; V _{DD(OSC)} = 3.3 V	•		•		•
f _{xtal}	crystal frequency		_	11.2896	_	MHz
V _{xtal}	voltage across the crystal	crystal series resistance $R_s < 100 \Omega$; crystal shunt capacitance $C_p < 7 pF$; crystal load capacitance $C_L = 12 pF$; $C_1 = C_2 = 22 pF$ (see Fig.13)	1.6	2.6	3.6	V
I _{DD(OSC)}	supply current crystal	at start-up	1.7	3.4	6.4	mA
	oscillator	at oscillation	_	0.32	-	mA

13 RDS AND I²S-BUS TIMING

 T_{amb} = 25 °C; V_{DDD} = 3.3 V; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
RDS timing (se	ee Figs 18 and 19)	-	•		•	•
f _{RDSCLK}	nominal RDS clock frequency		_	1187.5	-	Hz
t _{su}	clock set-up time	direct output mode	100	-	-	μs
T _{cy}	cycle time	direct output mode	-	842	-	μs
		buffer mode	2	-	-	μs
t _{HC}	clock HIGH time	direct output mode	220	_	640	μs
		buffer mode	1	-	-	μs
t _{LC}	clock LOW time	direct output mode	220	-	640	μs
		buffer mode	1	_	-	μs
t _h	data hold time		100	-	-	μs
t _w	wait time	buffer mode	1	-	-	μs

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I ² S-bus timing	(see Fig.23)		•	•		•
tr	rise time	T _{cy} = 325 ns	_	-	0.15T _{cy}	ns
t _f	fall time	T _{cy} = 325 ns	-	-	0.15T _{cy}	ns
T _{cy}	bit clock cycle time		325	-	_	ns
t _{BCK(H)}	bit clock time HIGH	T _{cy} = 325 ns	0.35T _{cy}	-	-	ns
t _{BCK(L)}	bit clock time LOW	T _{cy} = 325 ns	0.35T _{cy}	-	_	ns
t _{su(D)}	data set-up time	T _{cy} = 325 ns	0.2T _{cy}	-	-	ns
t _{h(D)}	data hold time	T _{cy} = 325 ns	0.2T _{cy}	-	-	ns
t _{d(D)}	data delay time	T _{cy} = 325 ns	-	-	0.15T _{cy}	ns
t _{su(WS)}	word select set-up time	T _{cy} = 325 ns	0.2T _{cy}	-	-	ns
t _{h(WS)}	word select hold time	T _{cy} = 325 ns	0.2T _{cy}	-	_	ns



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14 I²C-BUS TIMING

 T_{amb} = 25 °C; V_{DDD} = 3.3 V; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	-	ARD MODE C-BUS	FAST MOD	DE I ² C-BUS	
			MIN.	MAX.	MIN.	MAX.	1
f _{SCL}	SCL clock frequency		0	100	0	400	kHz
t _{BUF}	bus free time between a STOP and START condition		4.7	-	1.3	_	μs
t _{HD;STA}	hold time (repeated) START condition. After this period, the first clock pulse is generated		4.0	-	0.6	-	μs
t _{LOW}	LOW period of the SCL clock		4.7	-	1.3	-	μs
t _{HIGH}	HIGH period of the SCL clock		4.0	-	0.6	-	μs
t _{SU;STA}	set-up time for a repeated START condition		4.7	-	0.6	-	μs
t _{HD;DAT}	data hold time		0	-	0	0.9	μs
t _{SU;DAT}	data set-up time		250	-	100	_	ns
t _r	rise time of both SDA and SCL signals	C _b in pF	-	1000	20 + 0.1C _b	300	ns
t _f	fall time of both SDA and SCL signals	C _b in pF	-	300	20 + 0.1C _b	300	ns
t _{SU;STO}	set-up time for STOP condition		4.0	-	0.6	-	μs
C _b	capacitive load for each bus line		-	400	-	400	pF
t _{SP}	pulse width of spikes to be suppressed by input filter		-	-	0	50	ns

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15 SOFTWARE DESCRIPTION

The use and description of the software features of the SAA7706H will be described in the separate application manual.

16 APPLICATION DIAGRAM

The application diagram shown in Figs 25 and 26 must be considered as one of the examples of a (limited) application of the chip e.g. in this case the I^2S -bus inputs of the CD-input are not used. For the real application set-up the information of the application report is necessary.





17 PACKAGE OUTLINE



18 SOLDERING

18.1 Introduction to soldering surface mount packages

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"Data Handbook IC26; Integrated Circuit Packages"* (document order number 9398 652 90011).

There is no soldering method that is ideal for all surface mount IC packages. Wave soldering can still be used for certain surface mount ICs, but it is not suitable for fine pitch SMDs. In these situations reflow soldering is recommended.

18.2 Reflow soldering

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several methods exist for reflowing; for example, convection or convection/infrared heating in a conveyor type oven. Throughput times (preheating, soldering and cooling) vary between 100 and 200 seconds depending on heating method.

Typical reflow peak temperatures range from 215 to 250 °C. The top-surface temperature of the packages should preferable be kept below 220 °C for thick/large packages, and below 235 °C for small/thin packages.

18.3 Wave soldering

Conventional single wave soldering is not recommended for surface mount devices (SMDs) or printed-circuit boards with a high component density, as solder bridging and non-wetting can present major problems.

To overcome these problems the double-wave soldering method was specifically developed.

If wave soldering is used the following conditions must be observed for optimal results:

- Use a double-wave soldering method comprising a turbulent wave with high upward pressure followed by a smooth laminar wave.
- For packages with leads on two sides and a pitch (e):
 - larger than or equal to 1.27 mm, the footprint longitudinal axis is preferred to be parallel to the transport direction of the printed-circuit board;
 - smaller than 1.27 mm, the footprint longitudinal axis must be parallel to the transport direction of the printed-circuit board.

The footprint must incorporate solder thieves at the downstream end.

• For packages with leads on four sides, the footprint must be placed at a 45° angle to the transport direction of the printed-circuit board. The footprint must incorporate solder thieves downstream and at the side corners.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Typical dwell time is 4 seconds at 250 °C. A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

18.4 Manual soldering

Fix the component by first soldering two diagonally-opposite end leads. Use a low voltage (24 V or less) soldering iron applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to $300 \,^{\circ}$ C.

When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 $^\circ\text{C}.$

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18.5 Suitability of surface mount IC packages for wave and reflow soldering methods

PACKAGE	SOLDERING METHOD			
FACKAGE	WAVE	REFLOW ⁽¹⁾		
BGA, LFBGA, SQFP, TFBGA	not suitable	suitable		
HBCC, HLQFP, HSQFP, HSOP, HTQFP, HTSSOP, SMS	not suitable ⁽²⁾	suitable		
PLCC ⁽³⁾ , SO, SOJ	suitable	suitable		
LQFP, QFP, TQFP	not recommended ⁽³⁾⁽⁴⁾	suitable		
SSOP, TSSOP, VSO	not recommended ⁽⁵⁾	suitable		

Notes

- 1. All surface mount (SMD) packages are moisture sensitive. Depending upon the moisture content, the maximum temperature (with respect to time) and body size of the package, there is a risk that internal or external package cracks may occur due to vaporization of the moisture in them (the so called popcorn effect). For details, refer to the Drypack information in the "Data Handbook IC26; Integrated Circuit Packages; Section: Packing Methods".
- 2. These packages are not suitable for wave soldering as a solder joint between the printed-circuit board and heatsink (at bottom version) can not be achieved, and as solder may stick to the heatsink (on top version).
- 3. If wave soldering is considered, then the package must be placed at a 45° angle to the solder wave direction. The package footprint must incorporate solder thieves downstream and at the side corners.
- 4. Wave soldering is only suitable for LQFP, TQFP and QFP packages with a pitch (e) equal to or larger than 0.8 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.65 mm.
- 5. Wave soldering is only suitable for SSOP and TSSOP packages with a pitch (e) equal to or larger than 0.65 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.5 mm.

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19 DATA SHEET STATUS

DATA SHEET STATUS	PRODUCT STATUS	DEFINITIONS (1)
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

Note

1. Please consult the most recently issued data sheet before initiating or completing a design.

20 DEFINITIONS

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information — Applications that are described herein for any of these products are for illustrative purposes only. Philips Semiconductors make no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

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Purchase of Philips I²C components conveys a license under the Philips' I²C patent to use the components in the I²C system provided the system conforms to the I²C specification defined by Philips. This specification can be ordered using the code 9398 393 40011.

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